## Low reverse leakage Schottky diode

## Description

```
Lead (PB) Free
    poHS}6\mathrm{ fully
    MoH'6 fully
```

Lifecycle status: Active


Features

General purpose Schottky diode in a broad range of package configurations. Optimised for High voltage clamp or analog DC switch applications. For low breakdown applciations, like detectors or mixers, please refer to HSMS-282X. For low flicker (1/F) noise applications refer to HSMS-281X. VBR=70 V, CT=2.0pF, RD=35 Ohms, Vf @ $1 \mathrm{~mA}=410 \mathrm{mV}$.

## Data Sheet



Lead (Pb) Free RoHS 6 fully compliant

## Description/Applications

These Schottky diodes are specifically designed for both analog and digital applications. This series offers a wide range of specifications and package configurations to give the designer wide flexibility. The HSMS-280x series of diodes is optimized for high voltage applications.

Note that Avago's manufacturing techniques assure that dice found in pairs and quads are taken from adjacent sites on the wafer, assuring the highest degree of match.

Package Lead Code Identification, SOT-323 (Top View)


Package Lead Code Identification, SOT-23/SOT-143 (Top View)


UNCONNECTED
BRIDGE


## Pin Connections and Package Marking, SOT-363



Absolute Maximum Ratings ${ }^{[1]} \mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}$

| Symbol | Parameter | Unit | SOT-23/SOT-143 | SOT-323/SOT-363 |
| :--- | :--- | :--- | :--- | :--- |
| $\mathrm{I}_{\mathrm{f}}$ | Forward Current (1 $\mu \mathrm{S}$ Pulse) | Amp | $\mathbf{1}$ | $\mathbf{1}$ |
| $\mathrm{P}_{\mathrm{IV}}$ | Peak Inverse Voltage | V | Same as $\mathrm{V}_{\text {BR }}$ | Same as $\mathrm{V}_{\text {BR }}$ |
| $\mathrm{T}_{\mathrm{j}}$ | Junction Temperature | ${ }^{\circ} \mathrm{C}$ | 150 | 150 |
| $\mathrm{~T}_{\text {stg }}$ | Storage Temperature | ${ }^{\circ} \mathrm{C}$ | -65 to 150 | -65 to 150 |
| $\theta_{\mathrm{jc}}$ | Thermal Resistance ${ }^{[2]}$ | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ | $\mathbf{5 0 0}$ | $\mathbf{1 5 0}$ |

## Notes:

1. Operation in excess of any one of these conditions may result in permanent damage to the device.
2. $T_{C}=+25^{\circ} \mathrm{C}$, where $T_{C}$ is defined to be the temperature at the package pins where contact is made to the circuit board.

## Electrical Specifications $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, Single Diode ${ }^{[3]}$

| Part Number HSMS ${ }^{[4]}$ | Package Marking Code | Lead <br> Code | Configuration | Minimum <br> Breakdown Voltage $V_{B R}(V)$ | Maximum <br> Forward <br> Voltage <br> $V_{F}(\mathrm{mV})$ | Maximum <br> Forward Voltage $V_{F}(V) @ I_{F}(m A)$ | Maximum <br> Reverse <br> Leakage $I_{R}(n A) @ V_{R}(V)$ | Maximum Capacitance $\mathrm{C}_{\mathrm{T}}(\mathrm{pF})$ | Typical Dynamic Resistance $R_{D}(\Omega)^{[5]}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 2800 | A0 | 0 | Single | 70 | 410 | 1.0 @ 15 | 200 @ 50 | 2.0 | 35 |
| 2802 | A2 | 2 | Series |  |  |  |  |  |  |
| 2803 | A3 | 3 | Common Anode |  |  |  |  |  |  |
| 2804 | A4 | 4 | Common Cathode |  |  |  |  |  |  |
| 2805 | A5 | 5 | Unconnected Pair |  |  |  |  |  |  |
| 2808 | A8 | 8 | Bridge Quad ${ }^{[4]}$ |  |  |  |  |  |  |
| 280B | A0 | B | Single |  |  |  |  |  |  |
| 280C | A2 | C | Series |  |  |  |  |  |  |
| 280E | A3 | E | Common Anode |  |  |  |  |  |  |
| 280F | A4 | F | Common Cathode |  |  |  |  |  |  |
| 280K | AK | K | High Isolation Unconnected Pair |  |  |  |  |  |  |
| 280L | AL | L | Unconnected Trio |  |  |  |  |  |  |
| 280M | H | M | Common Cathode Quad |  |  |  |  |  |  |
| 280N | N | N | Common Anode Quad |  |  |  |  |  |  |
| 280P | AP | P | Bridge Quad |  |  |  |  |  |  |
| 280R | 0 | R | Ring Quad |  |  |  |  |  |  |
| Test Conditions |  |  |  | $\mathrm{I}_{\mathrm{R}}=10 \mathrm{~mA}$ | $\mathrm{I}_{\mathrm{F}}=1 \mathrm{~mA}$ |  |  | $\begin{gathered} V_{F}=0 V \\ f=1 M H z \end{gathered}$ | $\mathrm{I}_{\mathrm{F}}=5 \mathrm{~mA}$ |

## Notes:

1. $D V_{\mathrm{F}}$ for diodes in pairs and quads in 15 mV maximum at 1 mA .
2. $\mathrm{DC}_{\mathrm{TO}}$ for diodes in pairs and quads is 0.2 pF maximum.
3. Effective Carrier Lifetime ( t ) for all these diodes is 100 ps maximum measured with Krakauer method at 5 mA .
4. See section titled "Quad Capacitance."
5. $R_{D}=R_{S}+5.2 \Omega$ at $25^{\circ} \mathrm{C}$ and $\mathrm{I}_{\mathrm{f}}=5 \mathrm{~mA}$.

## Applications Information Introduction Product Selection

Avago's family of Schottky products provides unique solutions to many design problems.

The first step in choosing the right product is to select the diode type. All of the products in the HSMS-280x family use the same diode chip, and the same is true of the HSMS-281x and HSMS-282x families. Each family has a different set of characteristics which can be compared most easily by consulting the SPICE parameters in Table 1.

A review of these data shows that the HSMS-280x family has the highest breakdown voltage, but at the expense of a high value of series resistance $\left(R_{s}\right)$. In applications which do not require high voltage the HSMS-282x family, with a lower value of series resistance, will offer higher current carrying capacity and better performance. The HSMS-281x family is a hybrid Schottky (as is the HSMS-280x), offering lower 1/f or flicker noise than the HSMS-282x family.

In general, the HSMS-282x family should be the designer's first choice, with the -280x family reserved for high voltage applications and the HSMS-281x family for low flicker noise applications.

## Assembly Instructions

## SOT-323 PCB Footprint

A recommended PCB pad layout for the miniature SOT323 (SC-70) package is shown in Figure 6 (dimensions are in inches). This layout provides ample allowance for package placement by automated assembly equipment without adding parasitics that could impair the performance.


Figure 6. Recommended PCB Pad Layout for Avago's SC70 3L/SOT-323 Products.

## Assembly Instructions

## SOT-363 PCB Footprint

A recommended PCB pad layout for the miniature SOT363 (SC-70, 6 lead) package is shown in Figure 7 (dimensions are in inches). This layout provides ample allowance for package placement by automated assembly equipment without adding parasitics that could impair the performance.


Figure 7. Recommended PCB Pad Layout for Avago's SC70 6L/SOT-363 Products.

Table 1. Typical SPICE Parameters

| Parameter | Units | HSMS-280x | HSMS-281x | HSMS-282x |
| :--- | :--- | :--- | :--- | :--- |
| $\mathrm{B}_{\mathrm{V}}$ | V | 75 | 25 | 15 |
| $\mathrm{C}_{\mathrm{J} 0}$ | pF | 1.6 | 1.1 | 0.7 |
| $\mathrm{E}_{\mathrm{G}}$ | eV | 0.69 | 0.69 | 0.69 |
| $\mathrm{I}_{\mathrm{BV}}$ | A | $1 \mathrm{E}-5$ | $1 \mathrm{E}-5$ | $1 \mathrm{E}-4$ |
| $\mathrm{I}_{\mathrm{S}}$ | A | $3 \mathrm{E}-8$ | $4.8 \mathrm{E}-9$ | $2.2 \mathrm{E}-8$ |
| N |  | 1.08 | 1.08 | 1.08 |
| $\mathrm{R}_{\mathrm{S}}$ | $\Omega$ | 30 | 10 | 6 |
| $\mathrm{P}_{\mathrm{B}}(\mathrm{V})$ | V | 0.65 | 0.65 | 0.65 |
| $\mathrm{P}_{\mathrm{T}}(\mathrm{XTI})$ |  | 2 | 2 | 2 |
| M |  | 0.5 | 0.5 | 0.5 |

## Part Number Ordering Information

| Part Number | No. of <br> Devices | Container |
| :--- | :--- | :--- |
| HSMS-280x-TR2G | 10000 | 13"Reel |
| HSMS-280x-TR1G | 3000 | 7"Reel |
| HSMS-280x-BLKG | 100 | antistatic bag |

$x=0,2,3,4,5,8, B, C, E, F, K, L, M, N, P, R$

## Package Dimensions

## Outline 23 (SOT-23)



Notes:
XXX-package marking
Drawings are not to scale

|  | DIMENSIONS (mm) |  |
| :---: | :---: | :---: |
| SYMBOL | MIN. | MAX. |
| A | 0.79 | 1.20 |
| A1 | 0.000 | 0.100 |
| B | 0.37 | 0.54 |
| C | 0.086 | 0.152 |
| D | 2.73 | 3.13 |
| E1 | 1.15 | 1.50 |
| e | 0.89 | 1.02 |
| e1 | 1.78 | 2.04 |
| e2 | 0.45 | 0.60 |
| E | 2.10 | 2.70 |
| L | 0.45 | 0.69 |

Outline SOT-323 (SC-70 3 Lead)


## Package Dimensions (Continued)

Outline 143 (SOT-143)


Notes:
XXX-package marking
Drawings are not to scale

Outline SOT-363 (SC-70 6 Lead)


|  | DIMENSIONS (mm) |  |
| :---: | :---: | :---: |
| SYMBOL | MIN. | MAX. |
| E | 1.15 | 1.35 |
| D | 1.80 | 2.25 |
| HE | 1.80 | 2.40 |
| A | 0.80 | 1.10 |
| A2 | 0.80 | 1.00 |
| A1 | 0.00 | 0.10 |
| 01 | 0.10 | 0.40 |
| e | 0.650 |  |
| b | 0.15 | 0.30 |
| c | 0.10 | 0.20 |
| L | 0.10 | 0.30 |



## Device Orientation



For Outline SOT-143


Note: "AB" represents package marking code.
"C" represents date code.

For Outlines SOT-23,-323


Note: "AB" represents package marking code. "C" represents date code.

For Outline SOT-363


Note: "AB" represents package marking code.
" C " represents date code.

